

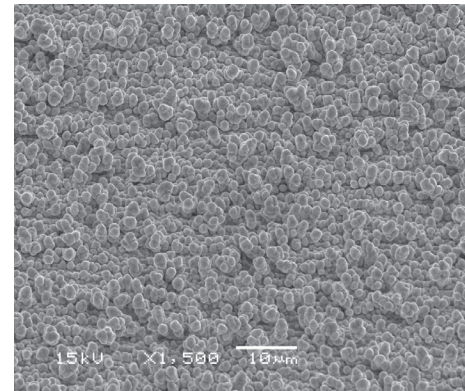
High temperature stability, reverse treat, electrodeposited copper foil.

**Applications:**

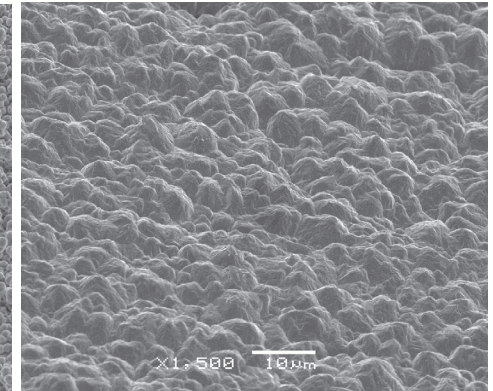
- PCB inner layers

**Features:**

- IPC Grade III
- Treatment on drum side of foil
- High temperature lamination compatible



Treated Drum Side  
0.5 Oz. 18µm (1500x)



Untreated Matte Side  
0.5 Oz. 18µm (1500x)

**Typical Values:**

Attribute		Unit	Value				Reference
Thickness Designation			H	1	2	3	IPC-4562, 1.2.5.1 Table 1-1; IPC-TM-650-2.2.12
Nominal Thickness		µm	18	35	70	103	
		oz.	1/2	1	2	3	
Area Weight		g/m <sup>2</sup>	152.5	305	610	915	
		g/254 in <sup>2</sup>	25	50	100	150	
		oz./ft <sup>2</sup>	0.5	1	2	3	
Roughness	Drum Side	µm	4.1				IPC-TM-650-2.2.17
		µ"	160				
	Matte Side	µm	4.5	5.7	8.9	15.0	
		µ"	175	225	350	590	
Tensile	Ambient	Kg/mm <sup>2</sup>	42.2	38.7	36.9	34.4	IPC-TM-650-2.4.18
		Kpsi	60	55	52.5	48.9	
	180°C	Kg/mm <sup>2</sup>	21				
		Kpsi	30				
Elongation	Ambient	%	8	15	20	26	
	180°C	%	8			7.2	
Peel Strength* (Drum/Treated Side)	Cond. B	Kg/cm	0.98	1.16	1.25	1.20	IPC-TM-650-2.4.8
		Lbs/in	5.5	6.5	7.0	6.7	

\* Peel strength measured on 170°C Tg Epoxy

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